

METHOD OF FORMING INTERLAYER CONNECTIONS IN INTEGRATED
OPTICAL CIRCUITS, AND DEVICES FORMED USING SAME

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ABSTRACT OF THE DISCLOSURE

A method and system of forming vertical optical interconnects in optical integrated circuits is disclosed. The method includes forming a first optical transmission layer over a substrate. A first cladding layer is then formed on the first optical transmission layer and portions of the first cladding layer removed to form an angled sidewall in the first cladding layer. An optical interconnect layer is formed on the angled sidewall of the first cladding layer and on an exposed portion of the first optical transmission layer.